

67,200-327
Serial Number 09/885,784



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AMENDMENT AND RESPONSE TO OFFICE ACTION

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TO: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

FROM: Tung & Associates
838 West Long Lake Road - Suite 120
Bloomfield Hills, MI 48302

DATE: 21 October 2002

REF: APPLICANT : Liang
SERIAL NO. : 09/885,784
ART UNIT : 2823
FILING DATE : 20 June 2001
ATT'Y NO. : 67,200-327
EXAMINER : Julio J. Maldonado
TITLE : Laminating Method for Forming Integrated Circuit
Microelectronic Fabrication

Sir:

In response to an office communication mailed on 30 August 2002, please consider the following amendments and remarks pertaining to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231 on 11/1 2002.

Kathy Dixon

11/1/02
Date

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Not responsive
do not enter
6/3/19/03